

Parameter	Rating	Units
AC Operating Voltage	120	V _{rms}
Load Current	1	A_{rms}
On State Voltage Drop	1.6	V_{rms} (at $I_L = 1A_{rms}$)

Features

- Load Current up to 1A_{rms}
- 400V_P Blocking Voltage
- 5mA Sensitivity
- · Zero-Crossing Detection
- DC Control, AC Output
- · Optically Isolated
- Low EMI and RFI Generation
- High Noise Immunity
- Flammability Rating UL 94 V-0

Applications

- Programmable Control
- Process Control
- · Power Control Panels
- Remote Switching
- · Gas Pump Electronics
- Contactors
- Large Relays
- Solenoids
- Motors
- Heaters

Description

The CPC1945G is an AC Solid State Relay (SSR) using patented waveguide coupling with dual power SCR outputs to produce an alternative to optocoupler and Triac circuits. The switches are robust enough to provide a blocking voltage of up to $400V_P$.

In addition, tightly controlled zero-cross circuitry ensures switching of AC loads without the generation of transients.

The input and output circuits are optically coupled to provide $3750V_{rms}$ of isolation and noise immunity between control and load circuits. As a result, the CPC1945G is well suited for industrial environments where electromagnetic interference could disrupt the operation of electromechanical relays.

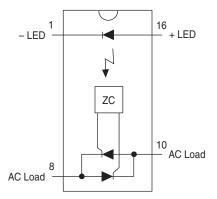
Approvals

- UL Recognized Component: File E69938
- CSA Certified Component: File 043639

Ordering Information

Part #	Description
CPC1945G	4-Pin (16-Pin Body) DIP (25/Tube)

Pin Configuration











Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	400	V_P
Reverse Input Voltage	5	V
Input Control Current	100	mA
Peak (10ms)	1	Α
Input Power Dissipation ¹	150	mW
P _{MAX} , Total Package Dissipation ²	1600	mW
Isolation Voltage, Input to Output	3750	V_{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 1.33 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Typical values are characteristic of the device at +25°C, and are the result of engineering evaluations. They are provided for information purposes only, and are not part of the manufacturing testing requirements.

Electrical Characteristics @ 25°C

rs	Conditions	Symbol	Min	Тур	Max	Units
naracteristics						
oltage Range	$V_{\rm L}$	-	20	-	120	V_{rms}
t, Continuous	$V_L = 120 V_{rms}$	IL	0.005	-	1	A _{rms}
ive Single Cycle Surge Current	-	I _{TSM}	-	-	10	A
akage Current	$V_L = 400 V_P$	I _{LEAK}	-	-	1	mA
Itage Drop	I _L =1A _{rms}		-	-	1.6	V _{rms}
of Rise ³	-	dV/dt	1000	-	-	V/µs
peeds						
	lΕmΛ	t _{on}	-	-	0.5	ovoloo
	I _F =5 mA	t _{off}	-	-	0.5	cycles
Turn-On Voltage ¹	1st half-cycle	-	-	2	10	V
Si	ubsequent half-cycle	-	-	1	-	V
requency	-	-	20	-	400	Hz
Factor for Guaranteed Turn-On ²	-	PF	0.25	-	-	-
racteristics						
I Current to Activate 4	-	I _F	-	0.8	5	mA
e Drop	I _F =5mA	V _F	0.9	1.2	1.5	V
out Voltage	-	-	0.8	-	-	V
ut Current	V _R =5V	I _R	-	-	10	μΑ
Characteristics						
out Capacitance	V _{IO} =0V, f=1MHz	C _{IO}	-	3	-	pF
ut Current Characteristics						

² Derate linearly 16.6 mW / °C

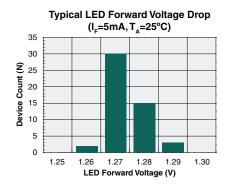
¹ Zero Cross 1st half-cycle @ <100Hz ² Snubber circuits may be required at low power factors.

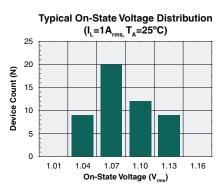
³ Tested in accordance with EIA/NARM standard RS-443.

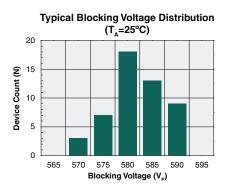
 $^{^4}$ For high noise environments, use I_F=10mA.

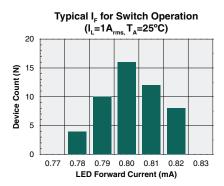


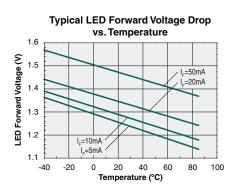
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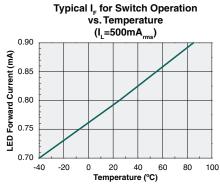


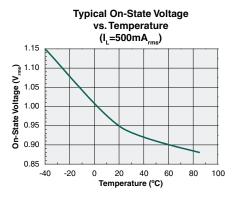






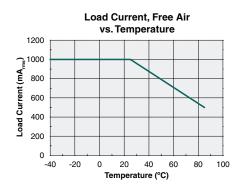


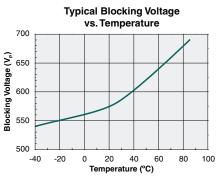


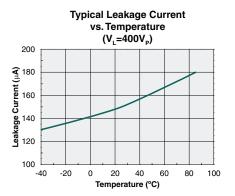


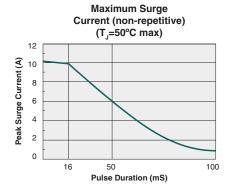


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Manufacturing Information

Moisture Sensitivity

All plastic encapsulated semiconductor packages are susceptible to moisture ingression. IXYS Integrated Circuits classifies its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, IPC/JEDEC J-STD-020, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a Moisture Sensitivity Level (MSL) classification as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Classification
CPC1945G	MSL 1

ESD Sensitivity



This product is ESD Sensitive, and should be handled according to the industry standard JESD-625.

Soldering Profile

Provided in the table below is the Classification Temperature (T_C) of this product and the maximum dwell time the body temperature of this device may be (T_C - 5)°C or greater. The classification temperature sets the Maximum Body Temperature allowed for this device during lead-free reflow processes. For through-hole devices, and any other processes, the guidelines of **J-STD-020** must be observed.

Device	Classification Temperature (T _c)	Dwell Time (t _p)	Max Reflow Cycles
CPC1945G	245°C	30 seconds	1

Board Wash

IXYS Integrated Circuits recommends the use of no-clean flux formulations. Board washing to reduce or remove flux residue following the solder reflow process is acceptable provided proper precautions are taken to prevent damage to the device. These precautions include, but are not limited to: using a low pressure wash and providing a follow up bake cycle sufficient to remove any moisture trapped within the device due to the washing process. Due to the variability of the wash parameters used to clean the board, determination of the bake temperature and duration necessary to remove the moisture trapped within the package is the responsibility of the user (assembler). Cleaning or drying methods that employ ultrasonic energy may damage the device and should not be used. Additionally, the device must not be exposed to flux or solvents that are Chlorine- or Fluorine-based.



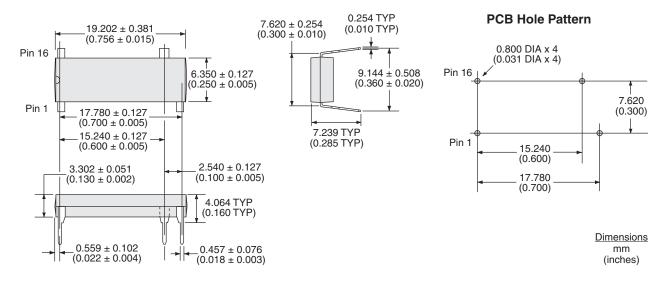






MECHANICAL DIMENSIONS

CPC1945G



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